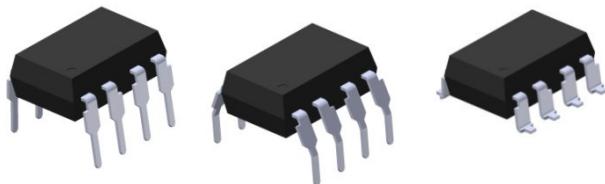


DATASHEET

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8 PIN DIP HIGH SPEED 1Mbit/s TRANSISTOR PHOTOCOUPLER 6N135 6N136 EL450x Series



Features

- High speed 1Mbit/s
- High isolation voltage between input and output ($V_{iso}=5000$ Vrms)
- Guaranteed performance from 0°C to 70°C
- Wide operating temperature range of -55°C to 100°C
- Pb free and RoHS compliant
- UL and cUL approved(No. E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved

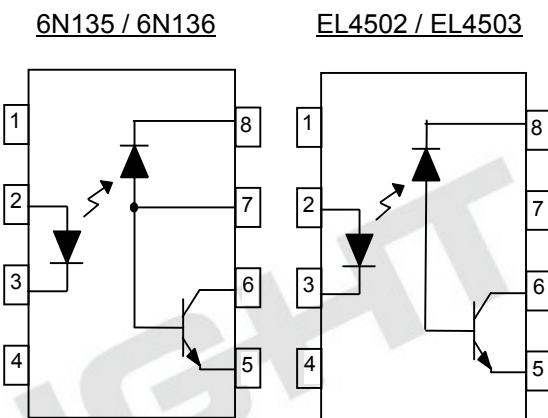
Description

The 6N135, 6N136, EL4502 and EL4503 devices each consist of an infrared emitting diode, optically coupled to a high speed photo detector transistor. A separate connection for the photodiode bias and output-transistor collector increase the speed by several orders of magnitude over conventional phototransistor couplers by reducing the base-collector capacitance of the input transistor. The devices are packaged in an 8-pin DIP package and available in wide-lead spacing and SMD option

Applications

- Line receivers
- Telecommunication equipments
- Power transistor isolation in motor drives
- Replacement for low speed phototransistor photo couplers
- Feedback loop in switch-mode power supplies
- Home appliances
- High speed logic ground isolation

Schematic



Pin Configuration

1. No Connection
2. Anode
3. Cathode
4. No Connection
5. Gnd
6. Vout
7. V_B
8. V_{CC}

Pin Configuration

1. No Connection
2. Anode
3. Cathode
4. No Connection
5. Gnd
6. Vout
7. No Connection
8. V_{CC}

Absolute Maximum Ratings (Ta=25 °C)

	Parameter	Symbol	Rating	Unit
Input	Forward current	I _F	25	mA
	Peak forward current (50% duty, 1ms P.W.)	I _{FP}	50	mA
	Peak transient current ($\leq 1\mu s$ P.W,300pps)	I _{trans}	1	A
	Reverse voltage	V _R	5	V
	Power dissipation	P _{IN}	45	mW
Output	Power dissipation	P _O	100	mW
	Emitter-Base reverse voltage 6N135 6N136	V _{EBR}	5	V
	Base current 6N135 6N136	I _B	5	mA
	Average Output current	I _{O(AVG)}	8	mA
	Peak Output current	I _{O(PK)}	16	mA
	Output voltage	V _O	-0.5 to 20	V
	Supply voltage	V _{CC}	-0.5 to 30	V
	Total Power Dissipation	P _{TOT}	200	mW
	Isolation Voltage*1	V _{ISO}	5000	Vrms
	Operating Temperature	T _{OPR}	-55 to 100	
	Storage Temperature	T _{STG}	-55 to 125	
	Soldering Temperature*2	T _{SOL}	260	

Notes:

*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2, 3, 4 are shorted together, and pins 5, 6, 7, 8 are shorted together.

*2 For 10 seconds

Electrical Characteristics ($T_A=0$ to 70°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V_F	-	1.45	1.8	V	$I_F = 16\text{mA}$
Reverse Voltage	V_R	5.0	-	-	V	$I_R = 10\mu\text{A}$
Temperature coefficient of forward voltage	$\Delta V_F/\Delta T_A$	-	-1.9	-	mV/ $^\circ\text{C}$	$I_F = 16\text{mA}$

Output

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Logic High Output Current	I_{OH}	-	0.001	0.5	μA	$I_F=0\text{mA}, V_O=V_{CC}=5.5\text{V}, T_A=25^\circ\text{C}$
		-	0.01	1		$I_F=0\text{mA}, V_O=V_{CC}=15\text{V}, T_A=25^\circ\text{C}$
		-	-	50		$I_F=0\text{mA}, V_O=V_{CC}=15\text{V}$
Logic Low Supply Current	I_{OCL}	-	140	200	μA	$I_F=16\text{mA}, V_O=\text{Open}, V_{CC}=15\text{V}$
Logic High Supply Current	I_{OCH}	-	0.01	1	μA	$I_F=0\text{mA}, V_O=\text{Open}, V_{CC}=15\text{V}, T_A=25^\circ\text{C}$
		-	-	2		$I_F=0\text{mA}, V_O=\text{Open}, V_{CC}=15\text{V}$

Transfer Characteristics ($T_A=0$ to 70°C unless specified otherwise)

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer Ratio	CTR	6N135	7	-	50	$I_F = 16\text{mA}, V_O = 0.4\text{V}, V_{CC}=4.5\text{V}, T_A=25^\circ\text{C}$
		6N136 EL4502 EL4503	19	-	50	
		6N135	5	-	-	
		6N136 EL4502 EL4503	15	-	-	
Logic Low Output Voltage	V_{OL}	6N135	-	0.18	0.4	$I_F = 16\text{mA}, I_O = 1.1\text{mA}, V_{CC}=4.5\text{V}, T_A=25^\circ\text{C}$
		6N136 EL4502 EL4503	-	0.25	0.4	
		6N135	-	-	0.5	
		6N136 EL4502 EL4503	-	-	0.5	

Switching Characteristics ($T_A=0$ to 70°C unless specified otherwise, $I_F=16\text{mA}$, $V_{cc}=5\text{V}$)

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Propagation Delay Time to Logic Low (Fig.8)	6N135	-	0.35	1.5	μs	$R_L = 4.1\text{K}\Omega$, $T_A = 25^\circ\text{C}$
		-	-	2.0		$R_L = 4.1\text{K}\Omega$
	TPHL	-	0.35	0.8		$R_L = 1.9\text{K}\Omega$, $T_A = 25^\circ\text{C}$
		-	-	1.0		$R_L = 1.9\text{K}\Omega$
Propagation Delay Time to Logic High (Fig.8)	6N135	-	0.5	1.5	μs	$R_L = 4.1\text{K}\Omega$, $T_A = 25^\circ\text{C}$
		-	-	2.0		$R_L = 4.1\text{K}\Omega$
	TPLH	-	0.3	0.8		$R_L = 1.9\text{K}\Omega$, $T_A = 25^\circ\text{C}$
		-	-	1.0		$R_L = 1.9\text{K}\Omega$
Common Mode Transient Immunity at Logic High (Fig.9)* ³	6N135	1,000	-	-	$\text{V}/\mu\text{s}$	$I_F = 0\text{mA}$, $V_{CM} = 10\text{Vp-p}$, $R_L = 4.1\text{K}\Omega$, $T_A = 25^\circ\text{C}$
	6N136	1,000	-	-		$I_F = 0\text{mA}$, $V_{CM} = 10\text{Vp-p}$, $R_L = 1.9\text{K}\Omega$, $T_A = 25^\circ\text{C}$
	EL4502	-	-	-		$I_F = 0\text{mA}$,
	EL4503	15000	20000	-		$V_{CM} = 1500\text{Vp-p}$, $R_L = 1.9\text{K}\Omega$, $T_A = 25^\circ\text{C}$
Common Mode Transient Immunity at Logic Low (Fig.9)* ³	6N135	1,000	-	-	$\text{V}/\mu\text{s}$	$I_F = 16\text{mA}$, $V_{CM} = 10\text{Vp-p}$, $R_L = 4.1\text{K}\Omega$, $T_A = 25^\circ\text{C}$
	6N136	1,000	-	-		$I_F = 16\text{mA}$,
	EL4502	-	-	-		$V_{CM} = 10\text{Vp-p}$, $R_L = 1.9\text{K}\Omega$, $T_A = 25^\circ\text{C}$
	EL4503	15000	20000	-		$I_F = 16\text{mA}$, $V_{CM} = 1500\text{Vp-p}$, $R_L = 1.9\text{K}\Omega$, $T_A = 25^\circ\text{C}$

* Typical values at $T_a = 25^\circ\text{C}$

Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs. Forward Voltage

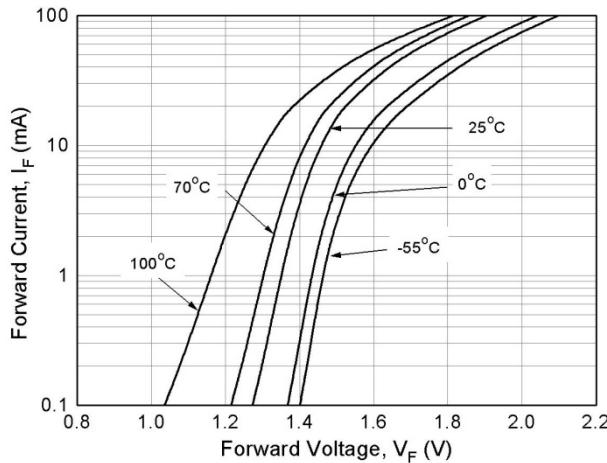


Fig.3 Normalized Current Transfer Ratio vs. Ambient Temperature

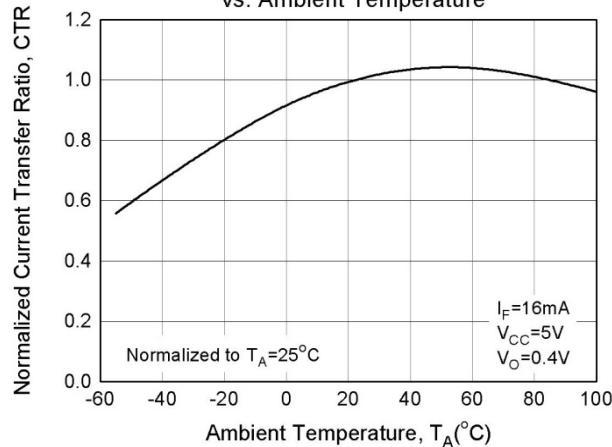


Fig.5 Logic High Output Current vs. Temperature

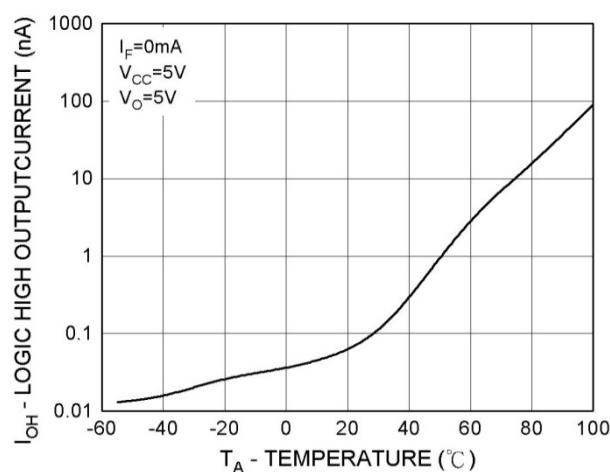


Fig.2 Normalized Current Transfer Ratio vs. Forward Current

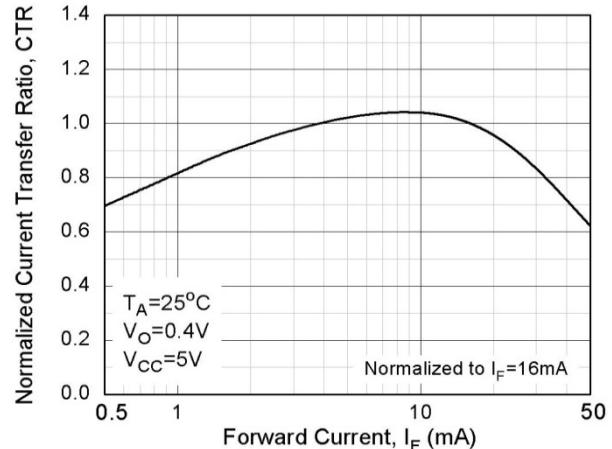


Fig.4 Output Current vs Output Voltage

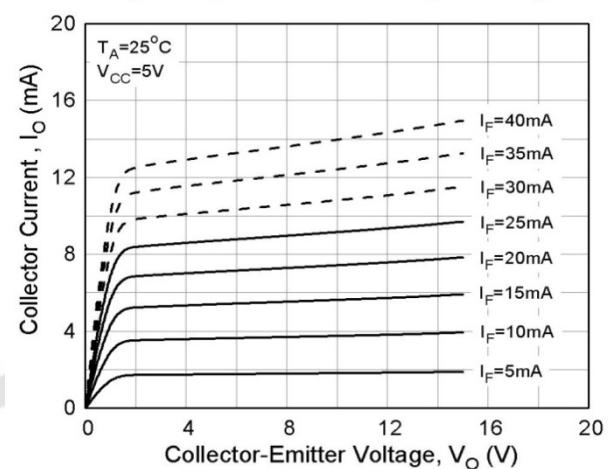


Fig.6 Propagation Delay vs. Load Resistance

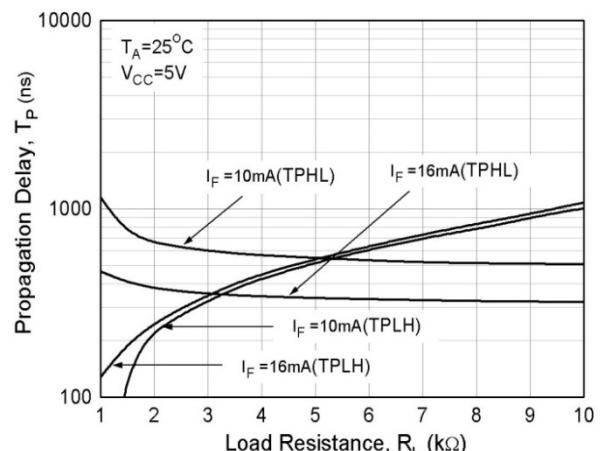


Fig.7 Propagation Delay vs. Temperature

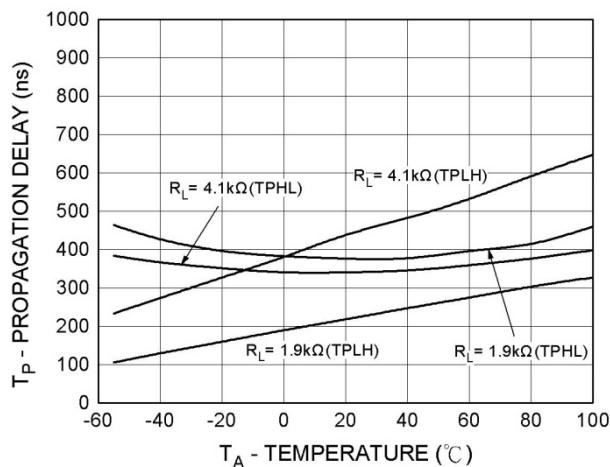


Figure 8 Switching Time Test Circuit & Waveform

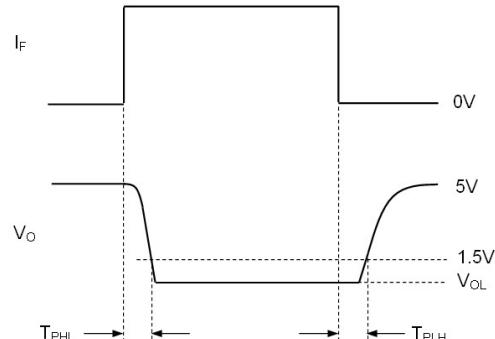
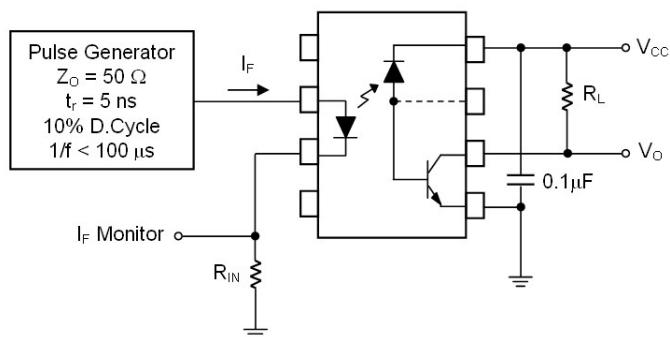
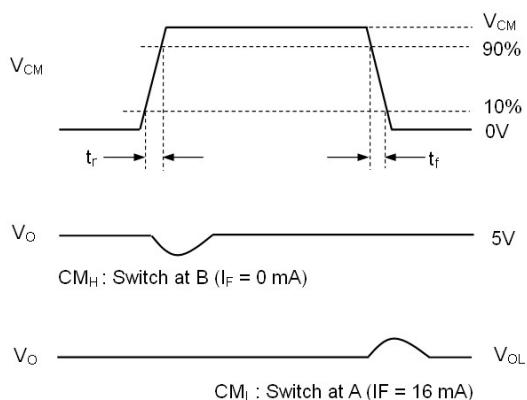
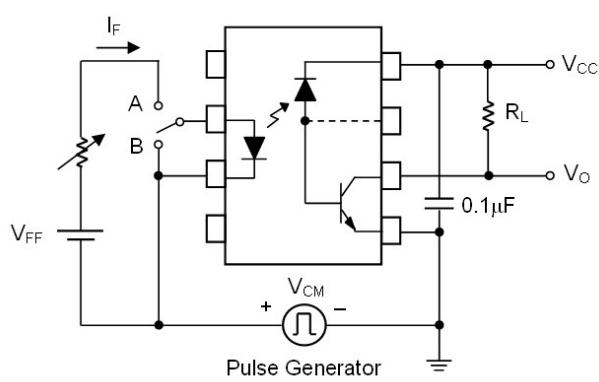


Figure 9 Transient Immunity Test Circuit & Waveform



Note:

*3 Common mode transient immunity in logic high level is the maximum tolerable (positive) dV_{cm}/dt on the leading edge of the common mode pulse signal V_{CM} , to assure that the output will remain in a logic high state (i.e., $V_O > 2.0V$).

Common mode transient immunity in logic low level is the maximum tolerable (negative) dV_{cm}/dt on the trailing edge of the common mode pulse signal, V_{CM} , to assure that the output will remain in a logic low state (i.e., $V_O < 0.8V$).

Order Information

Part Number

6N13XY(Z)-V

or

EL450XY(Z)-V

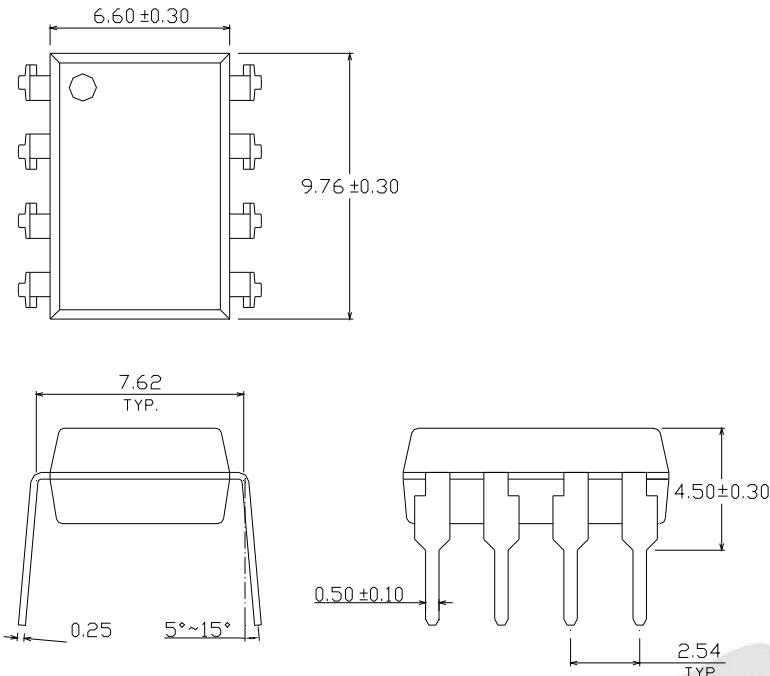
Note

- X = Part No. (X = 5 or 6) for 6N series; (X=2 or 3) for EL45 series
Y = Lead form option (S, S1, M or none)
Z = Tape and reel option (TA, TB or none)
V = VDE (optional)

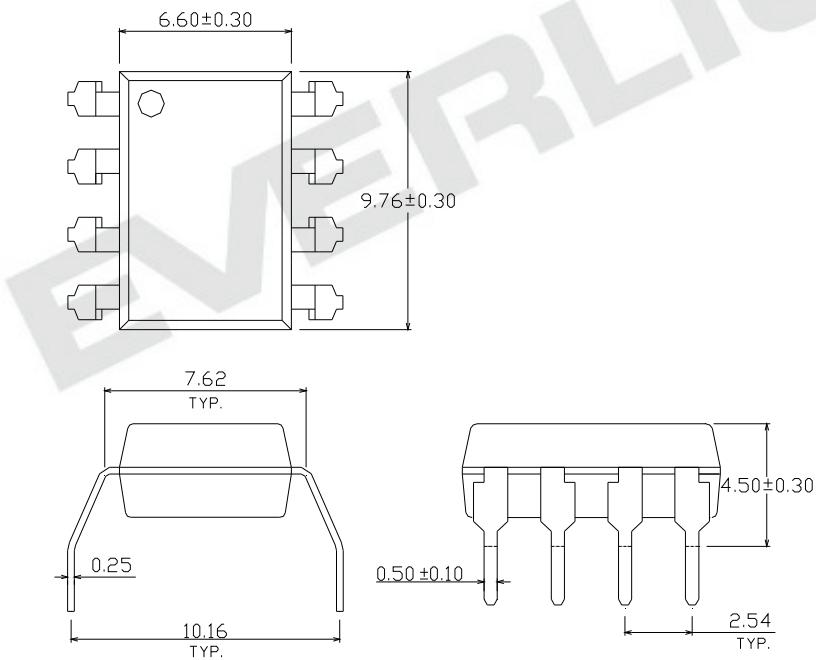
Option	Description	Packing quantity
None	Standard DIP-8	45 units per tube
M	Wide lead bend (0.4 inch spacing)	45 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel

Package Dimension
(Dimensions in mm)

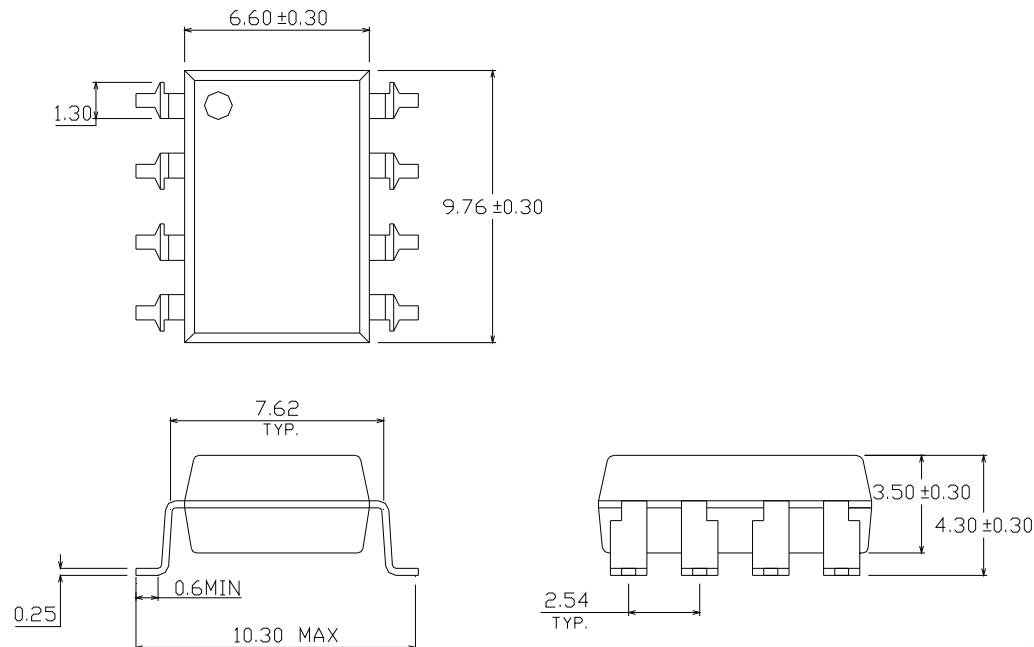
Standard DIP Type



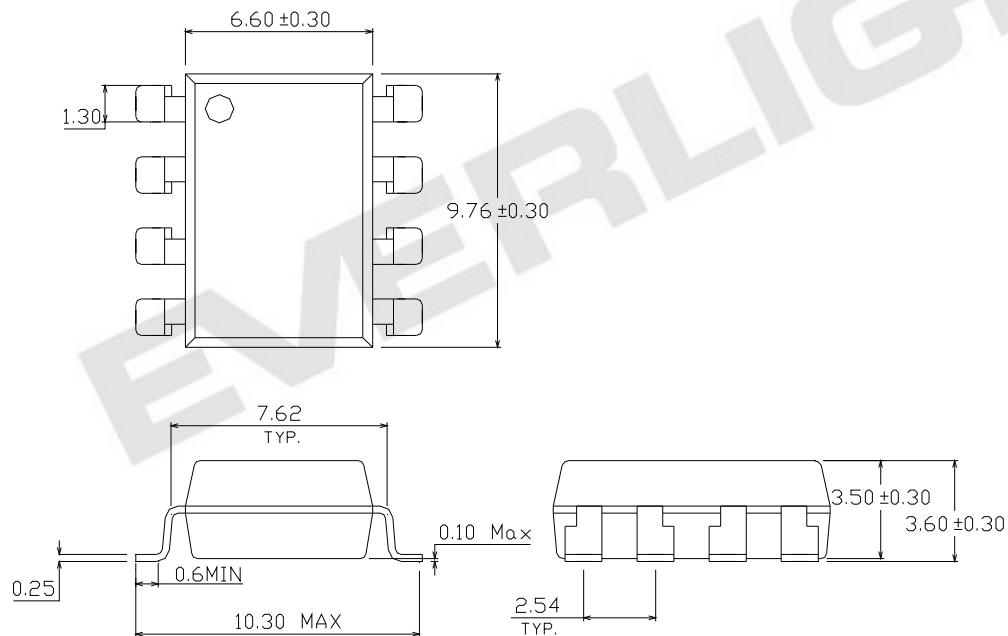
Option M Type



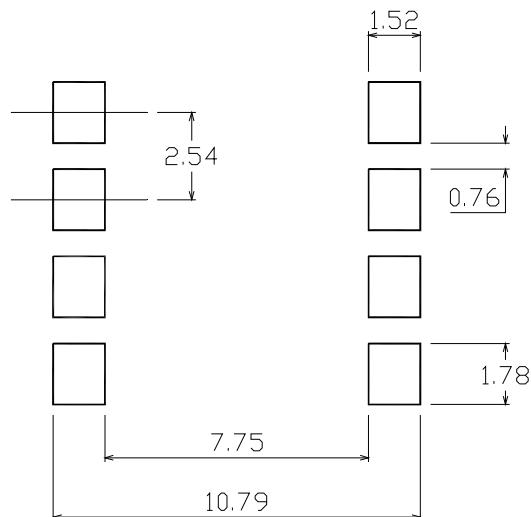
Option S Type



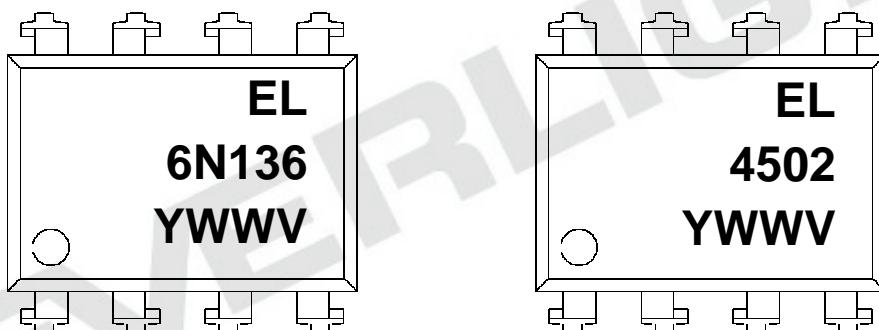
Option S1 Type



Recommended pad layout for surface mount leadform



Device Marking

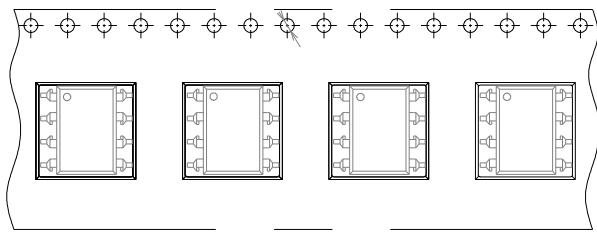


Notes

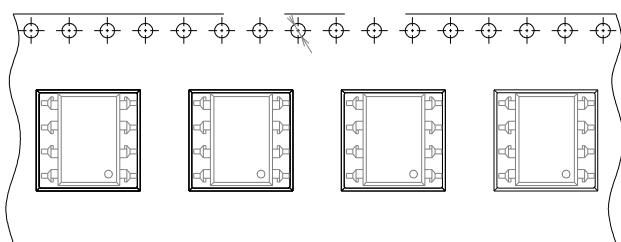
EL denotes EVERLIGHT
4502 denotes Device Number
6N136 denotes Device Number
Y denotes 1 digit Year code
WW denotes 2 digit Week code
V denotes VDE (optional)

Tape & Reel Packing Specifications

Option TA



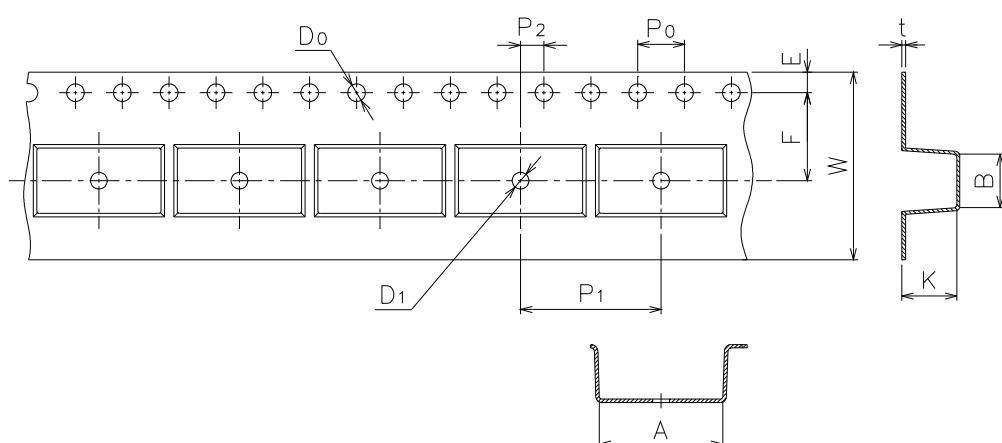
Option TB



Direction of feed from reel

Direction of feed from reel

Tape dimensions

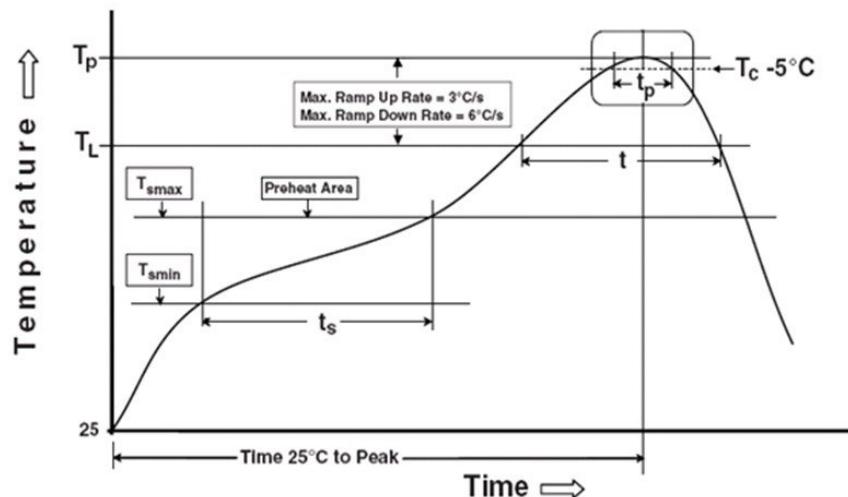


Dimension No.	A	B	D₀	D₁	E	F
Dimension(mm)	10.4 ± 0.1	10.0 ± 0.1	$1.5 + 0.1 / -0$	$1.5 \pm 0.25 / -0$	1.75 ± 0.1	7.5 ± 0.1
Dimension No.	P₀	P₁	P₂	t	W	K
Dimension(mm)	4.0 ± 0.1	12.0 ± 0.1	2.0 ± 0.05	0.4 ± 0.05	$16.0 \pm 0.3 /$	4.5 ± 0.1

Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200°C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_p)	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times

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